

Serial No. 10/771,461

Attorney Docket No. 01-588

LISTING OF CLAIMS:

1-6 (Canceled)

7. (Previously presented) A method of transporting a semiconductor dynamic sensor, which includes a semiconductor substrate, a displacement portion formed in the semiconductor substrate in beam structure, the displacement portion being displaceable in response to applied dynamic force, and a plurality of suction portions formed on a surface of the semiconductor substrate in regions separated from the displacement portion, each suction portion being a flat portion having an area larger than a predetermined area, wherein the method comprises:

placing, on the semiconductor substrate, a collet chuck having a plurality of tips having respective suction holes so that the tips contact the suction portions, each hole having an area smaller than the predetermined area of the flat portion;

drawing air through the holes to hold the semiconductor substrate by suction force applied to the suction portion; and

moving the collet chuck with the semiconductor substrate.

8. (Previously presented) The method according to claim 7, wherein the suction portions are formed at corners of the semiconductor substrate.

9. (Previously presented) The method according to claim 7, wherein the suction portions have no step portion and no wiring pattern to provide the flat portion.

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10. (Canceled)

11. (Canceled)